Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L-0410-07** DATE: 11/4/04
Product Affected: Selected Logic Mil-Grade products

Date Effective: February 3, 2005

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ■ Date Code Prefix (Stepping) change from "**K**" or "**P**" to "**PB**". (Please see attachment for detail)
- ☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment:: ■ Yes ☐ No

Samples: Available upon request

DESCRIPTION AND PURPOSE OF CHANGE:
- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

Selected Logic Mil-Grade products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon (Fab 4). There is no change in die technology. Please see attachment for the affected products.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY:

DATE:

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: L-0410-07

PCN Type: Fab Location Change

Data Sheet Change: None

Detail of Change: Selected Logic Mil-Grade products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon (Fab 4). There is no change in die technology. Please see below for the affected products:

Part Number	DSCC Part Number	Old Stepping	New Stepping
IDT54FCT245TDB	5962-9221401MRA	K, P	**PB**
IDT54FCT245ATDB	5962-9221403MRA	K, P	**PB**
IDT54FCT245CTDB	5962-9221405MRA	K, P	**PB**
IDT54FCT245TLB	5962-9221401M2A	K, P	**PB**
IDT54FCT245ATLB	5962-9221403M2A	K, P	**PB**
IDT54FCT245CTLB	5962-9221405M2A	K, P	**PB**
IDT54FCT574TDB	5962-9222201MRA	K, P	**PB**
IDT54FCT574ATDB	5962-9222203MRA	K, P	**PB**
IDT54FCT574CTDB	5962-9222205MRA	K, P	**PB**
IDT54FCT574TLB	5962-9222201M2A	K, P	**PB**
IDT54FCT574ATDB	5962-9222203M2A	K, P	**PB**
IDT54FCT574CTLB	5962-9222205M2A	K, P	**PB**

Qualification Plans: Following reliability tests were performed on the Mil-Grade parts.

The qualification results are as follow:

Test Description	Test Method	Required Sample/ # Fails	Test results (Mil-Grade)
Operating Life Test: Dynamic 184 hrs @ 150°C	Mil-Std 883 Method 1005	116/0	116/0
ESD Human Body Model	Mil-Std 883 Method 3015	3/0	2,500V
Latch up	EIA/JESD STD-78	6/0	6/0